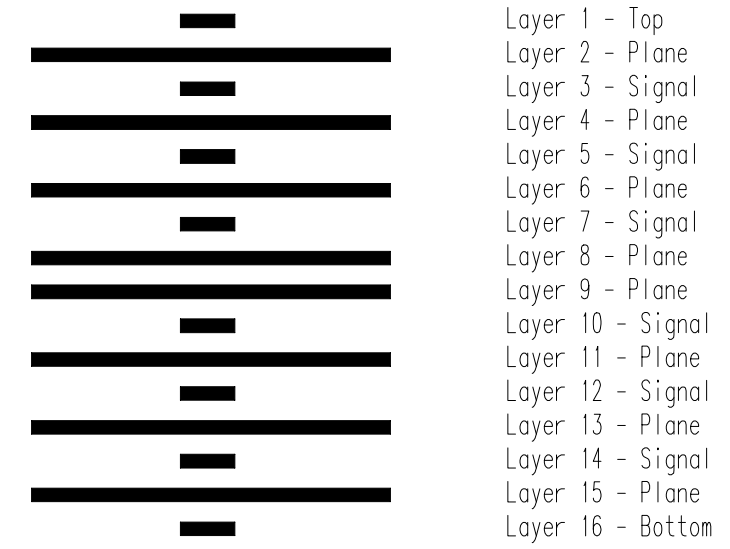


Note 9.

2.5mm

↑ Note 10.

Stackup- 16 Layer Board



Notes

1. Material -  $T_g > 180\text{ C}$ .
2. Electroless Nickel/Immersion Gold Plating: min 25um Cu, 2.5-5um Ni, 0.05-0.2um Au
3. Vias in pad must be filled with solid fills, planarized and plated over.
4. 1 Oz Cu on Top, Bottom and internal planes, 0.5 Oz Cu on internal signal layers.
5. Controlled Impedance: 58 Ohm - single ended, 99 Ohm - Differential
6. Board Thickness: 0.1" +/- 10%
7. Minimum Trace Width/Clearance: 4 mils
8. Remove all nonfunctional inner layer pads for pins and vias.
9. 45 Degree Chamfer
10. Mill 2.5mm on two edges of the board, on bottom side only, to a remaining thickness of 0.07" +/- 10%

Specifications Drawing  
PCB # 3019-Rev.A - DAMIC ACM Board

10/10/2022  
Mircea Bogdan  
The University of Chicago

Note 9.

2.5mm

↑ Note 10.